Product End-of-Life Disassembly Instructions

Product Category: Server
Marketing Name / Model [List multiple models if applicable.]
HP ProLiant ML110 G5 Pentium E2160 NHP-SATA
HP ProLiant ML110 G5 XEON 3065 NHP-SATA
HP ProLiant ML110 G5 XEON 3065 NHP-SAS
HP ProLiant ML110 G5 Model-F0 ALL
HP ProLiant ML110 G5 Model-F0 BRZL

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm MB, HP LO 100c Management Card, Gagarin LSI 4 port controller, PSU	4
Batteries	All types including standard alkaline and lithium coin or button style batteries Yes	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries No	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps No	0
Cathode Ray Tubes (CRT)	No	0
Capacitors / condensers (Containing PCB/PCT)	No	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Yes, there is one inside PSU.	1
External electrical cables and cords		0
Gas Discharge Lamps	No	0
Plastics containing Brominated Flame Retardants	No	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. No	0
Components and waste containing asbestos	No	0
Components, parts and materials containing refractory ceramic fibers	No	0

Components, parts and materials containing radioactive substances	No	0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

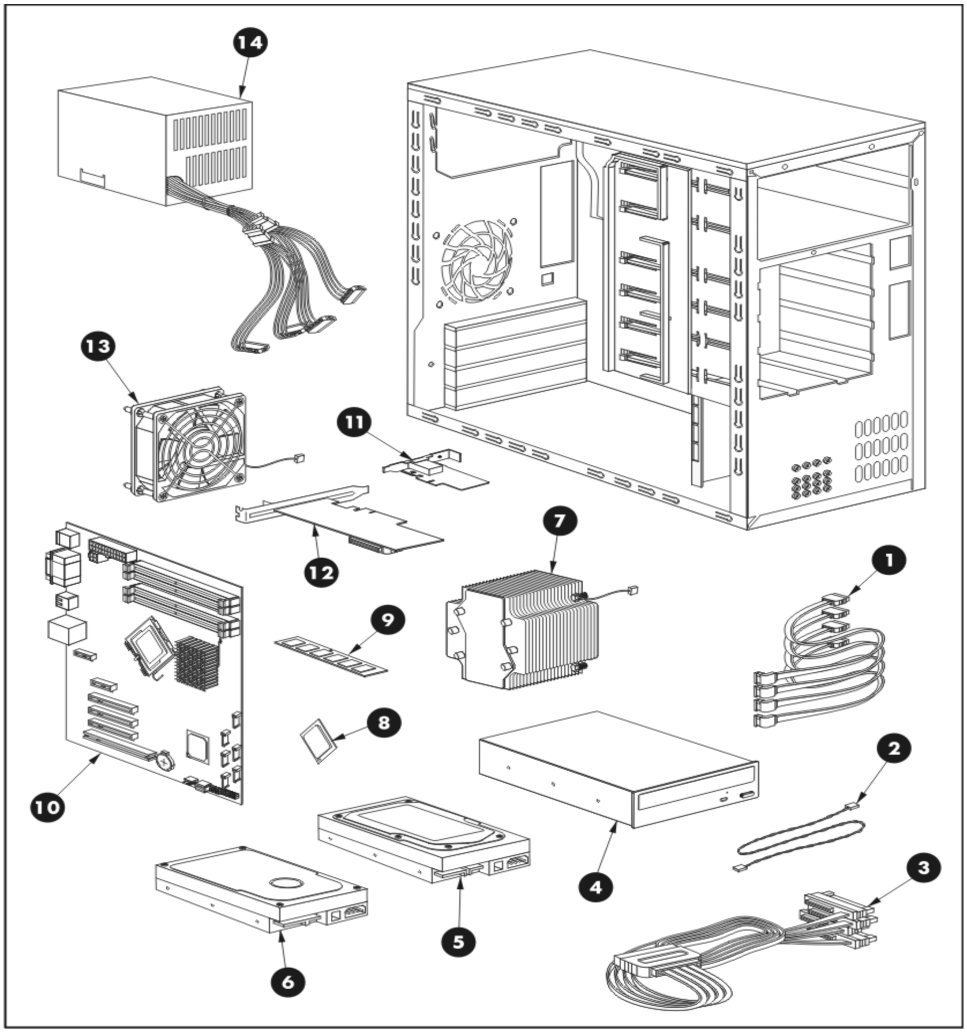
Tool Description	Tool Size (if applicable)
1. Screwdriver type “+”	#2 Philips
2. Torx screw driver	T-15
3. Flat head screw driver	Medium

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

To remove battery on the MB:
1. System Board Battery - Remove the chassis side cover and remove MB using a trox T-15 drive. (Attachment 1) Locate the battery on the system board.(Attachment 2) With a medium flat head screw driver, remove the battery and dispose of properly..
2. Capacitors=>2.5CM - Remove the power supply from the system using a torx T-15 driver.(Attachment 2) With #2 Philips screw driver, remove the screws securing the top cover, then locate the capacitors (attachment 3) and pry from the PCB with a medium flat head screw driver and dipose of properly.

Attachment 1



Attachment 2

Attachment 3